

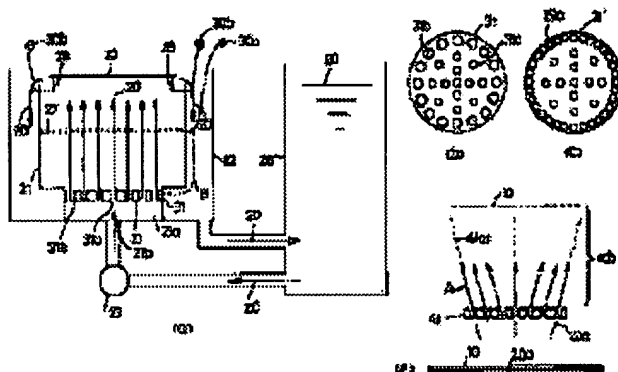
PLATING DEVICE

Patent number: JP5175158
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Classification:
- international: H01L21/288
- european:
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Abstract of JP5175158

PURPOSE:To provide a plating device which can coat a semiconductor wafer with a plated film having a uniform film thickness.

CONSTITUTION:In the title plating device which coats an object 10 to be plated with a plated film 20a by positioning the object 10 opposed to a stirring plate 31 which has a plurality of injecting holes for injecting a plating liquid 20 and is arranged in an injection cup 21 and injecting the plating liquid 20 through the holes, the stirring plate 31 is constituted so that the amount of the plating liquid injected through its outer peripheral section can become larger than that injected through its central part.



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